



162162

LEAD FREE TIN BASED SOLDER COMPOSITION



G00002

5

Abstract of the Disclosure

Lead-free solder alloys based on a Sn-Ag-Mg system are disclosed. The alloy compositions have a melting temperature close to 183 °C and a similar surface tension to that of Sn-Pb solder, and can thus be readily substituted for conventional Sn-Pb
10 solders. P may be added to the alloy compositions to reduce its tendency of oxidation.

Figure 1

- -